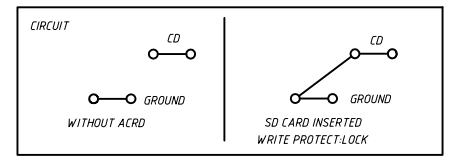
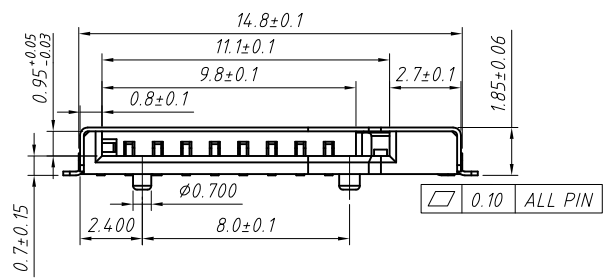


Material:
 Insulator: High Temperature Thermoplastic, LCP, UL 94V-0.
 Contact: Copper Alloy T=0.15, Plated 50u" Ni Overall. Plated Au Selective Contact Area Plated 30u"-70u" Sn Over Ni On Solder Area.
 Shell: T=0.15, Plated 30u" Ni Overall min. Plated 0.5u" Au Selective Contact Area.

Electrical:
 Current Rating: 0.5mA AC/DC amx.
 Voltage Rating: 125V AC/DC
 Ambient Temperature Range: -25°C ~ +85°C
 Storage Temperature Range: -25°C ~ +85°C
 Ambient Humidity Range: 95% R.H. Max.
 Contact Resistance: 100mΩ Max.
 Insulation Resistance: 1000MΩ Min./500VDC
 Mating Cycles: 5000 Insertions.
 Peak temperature: 260°C ±0.5°C



GENERAL TOLERANCE		ANGLE TOLERANCE		PROJECTION		Description:	
X	±0.15	X	±5°	UNITS	mm	Micro SD Card CONN; PUSH/ PUSH, H1.85mm, SMD with CD Pin, GOLD L-KLS1-TF-003C-H1.9-R	
.X	±0.03	.X	±3°	SHEET SIZE	A4		
.XX	±0.05	.XX	±2°	KLS P/N:			
Draw by:	Jenny	Date:	2018-03-10	 NingBo KLS ELECTRONIC CO., L TD.			
Check by:		Date:	2018-03-10				
SCALE		SHEET	1 OF 1				

